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Form PTO-1595

(Rev. 03/01)

OMB No. 0651-0027 (exp. 5/31/2002)

U.S. DEPARTMENT OF COMMERCE  
U.S. Patent and Trademark Office

103317069

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof

## 1. Name of conveying party(ies):

1) Kyung Su CHAE  
2) Hyun Ho SONG

Additional name(s) of conveying party(ies) attached?

☐ Yes ☒ No

## 3. Nature of Conveyance:

☒ Assignment ☐ Merger  
☐ Security Agreement ☐ Change of Name  
☐ OtherExecution Date: 1) November 6, 2003  
2) November 19, 2003

## 2. Name and address of receiving party(ies)

Name: LG.Philips LCD. Co., Ltd.

Internal Address:

Street Address:

20, Yoido-dong  
Youngdungpo-gu

City: Seoul

Country: Republic of Korea

Zip:

Additional name(s) &  
address(es) attached:☐ Yes ☒ No

## 4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the new application is: 11/6/03 and 11/19/03

A. Patent Application No.(s):

B. Patent No.(s):

Additional numbers attached?

☐ Yes ☒ No

## 5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Song K. Jung  
MCKENNA LONG & ALDRIDGE LLP

Internal Address: Atty. Dkt.: 8734.267.D1-US

Street Address:  
1900 K Street, N.W.

City:

Washington

State:

DC

Zip:

20006

## 6. Total number of applications and patents involved:

1

## 7. Total fee (37 CFR 3.41)

\$ 40.00

☒ Enclosed☐ Authorized to be charged to deposit account☐ Authorized to be charged to credit card  
(Form 2038 enclosed)

## 8. Deposit account number:

50-0911

(Attach duplicate copy of this page if paying by deposit account)

DO NOT USE THIS SPACE

## 9. Statement and signature.

*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*

Valerie P. Hayes; Reg. No.: 53,005

Name of Person Signing

Valerie P. Hayes

Signature

September 29, 2006

Date

Total number of pages including cover sheet, attachments, and documents: 3

112963 U.S. PTO  
11/529349

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10/02/2006 HLE333 00000146 11529349

05 FC:8021

40.00 OP

DC:50436020.1

PATENT  
REEL: 018365 FRAME: 0448

ASSIGNMENT

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention entitled:

Substrate Transfer System

for which I/WE executed an application for United States Letters Patent concurrently herewith; or filed an application for United States Letters Patent on \_\_\_\_\_, (Serial No. \_\_\_\_\_); and

WHEREAS, LG.Philips LCD Co., Ltd., a corporation of Korea, whose post office address is 20 Yoido-dong, Yongdungpo-Gu, Seoul, Korea, (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to be issue upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from assignee is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys I/WE have empowered in the Declaration and Power of Attorney in this application, to insert here in parentheses (Application No. \_\_\_\_\_, filed \_\_\_\_\_) the filing date and application number of said application when known.

December 5, 2003

IN TESTIMONY WHEREOF, I/WE have hereunto set our hand(s).

Full Name of Sole or First Assignor Kyung-Su CHAE	Assignor's Signature <i>Chae. Kyung Su.</i>	Date 2003. 11. 6
Address: Bosung APT. 105-602, Eumnae-Dong 1366-2, Bukgu, Daegu, Korea		Citizenship Republic of Korea
Full Name of Second Assignor Hyun-Ho SONG	Assignor's Signature	Date
Address: 601-705 Whajingeumbong 5cha, Hwangsan-Dong, Gumi, Gyungsangbuk-Do, Korea		Citizenship Republic of Korea
Full Name of Third Assignor	Assignor's Signature	Date
Address		Citizenship
Names of additional inventors attached <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No		

Morgan, Lewis & Bockius LLP

1-WA/2062781.1

ASSIGNMENT

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention entitled:

Substrate Transfer System

for which I/WE executed an application for United States Letters Patent concurrently herewith; or filed an application for United States Letters Patent on \_\_\_\_\_, (Serial No. \_\_\_\_\_); and

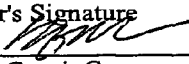
WHEREAS, LG Philips LCD Co., Ltd., a corporation of Korea, whose post office address is 20 Yoido-dong, Yongdungpo-Gu, Seoul, Korea, (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to be issue upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from assignee is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

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December 5, 2003

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Full Name of Sole or First Assignor Kyung-Su CHAE	Assignor's Signature	Date
Address: Bosung APT. 105-602, Eumnae-Dong 1366-2, Bukgu, Daegu, Korea		Citizenship Republic of Korea
Full Name of Second Assignor Hyun-Ho SONG	Assignor's Signature 	Date 03' 11.19
Address: 601-705 Whajingeumbong 5cha, Hwangsan-Dong, Gumi, Gyung-sangbuk-Do, Korea		Citizenship Republic of Korea
Full Name of Third Assignor	Assignor's Signature	Date
Address		Citizenship
Names of additional inventors attached <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No		

Morgan, Lewis & Bockius LLP

1-WA/2062781.1